



An experimentally-validated multi-scale materials, process and device modelling & design platform enabling non-expert access to open innovation in the Organic and Large Area Electronics Industry (MUSICODE)

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Publishable summary

The vision and target of MUSICODE is to provide an Open Innovation Platform for Materials Modelling. It consists of three conceptual layers: interface layer, data management layer and execution layer. Interfacing the platform with HPC resources is a task performed by the execution layer. In this report we describe the adopted approach used to connect the execution layer to the external 3rd party HPC resources. The actual integration is documented on selected examples of simulation workflows utilizing external HPC resources. Finally, the 3rd party offers, provisioning the service after the project termination and the serving of potential platform customers, are presented.